

4TH ELECTRONICS SYSTEM

ESTC 2012

INTEGRATION TECHNOLOGIES CONFERENCE

SEPTEMBER 17 - 20, 2012, AMSTERDAM RAI

Join us in Amsterdam for the Fourth Electronics System Integration Technology Conference!

We are honored to announce the ESTC 2012 Conference which is to take place at the RAI Conference and Exhibition Centre of Amsterdam, The Netherlands, 17-20 September 2012.

Organized by IEEE-CPMT since 2006, in association with IMAPS-Europe, the Electronics System Integration Technology Conferences (ESTC) conference series is the premier global European event that brings together key researchers, innovators, decision-makers, technologists, businesses, and professional associations working in interconnect and packaging technologies for electronic system integration in order to present, demonstrate, and discuss the latest developments in assembly and interconnection technology and new innovative applications.

Just like its highly successful predecessor events in Dresden (2006), Greenwich (2008) and Berlin (2010), ESTC 2012 will again feature a powerful technical program, as well as professional short courses on various microelectronic packaging technologies. The concurrent exhibition will facilitate the presentation of state-of-the-art technological services and equipment to an interested audience of international decision-makers from science and industry.

Call for Papers

ESTC 2012 seeks original papers describing research in all areas of electronic packaging.

Paper abstracts may be submitted to the following tracks: and application areas:

- Assembly and Manufacturing Technology
- Materials for Interconnect and Packaging
- Reliability
- Embedded die and Wafer Level Packaging
- 3D Integration Technology
- Microsystem Packaging
- Flexible and Stretchable electronics
- Advanced and Emerging Technologies
- Power Electronic Packaging
- Optoelectronic Packaging
- Thermal and Mechanical Modeling
- Electrical Design & Modeling
- Consumer Electronics
- Automotive and Industrial Electronics
- Avionics and Space Electronics
- Medical Electronics
- Solid state lighting
- Telecom system electronics
- Wireless electronics
- RF-ID and smartcards
- Display and imager electronics
- Energy System Electronics

More detailed information on the individual tracks can be found at www.estc2012.eu. Please indicate up to two major topics as listed above that your paper should be assigned to and one or more application area.

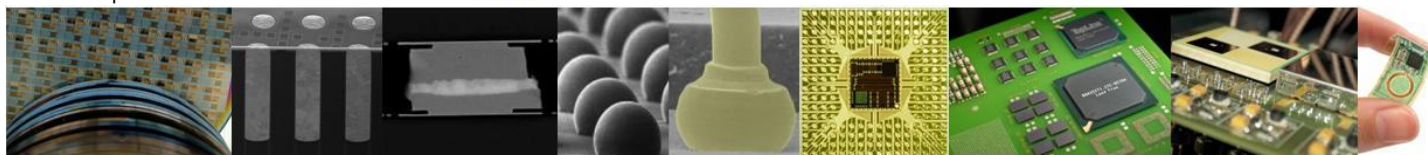


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Paper Submission

You are invited to submit a 300-500 word abstract that describes the scope, content and key points of your proposed paper. Abstracts must include results and graphics. Please visit www.estc2012.eu to upload your abstract. Submissions for poster presentations are also welcome. The official language of all presentations is English. All oral and poster presentation authors are invited to prepare a paper for the conference proceeding which will also be included in the IEEE XPLORE database after the conference.

The abstract must be received by April 1, 2012. Your submission must include the mailing address, business telephone number and email address of the presenting author and affiliations of all authors. All submitted abstracts will be reviewed by the committee to ensure a high-quality conference. Authors will be notified of paper acceptance with instructions for publication by June 1, 2012. At the discretion of the program committee, paper abstracts submitted may be considered for poster presentation. Manuscripts are due in final form for publication in the Conference Proceedings by August 15, 2012. The work should be original and not previously published, and avoid inclusion of commercial content. Additional instructions about formatting the paper will be published on www.estc2012.eu.

Best Presentation Award and Best Poster Award:

ESTC will select the best paper and best poster presentations. For each, the author(s) will receive a personalized ESTC award and share a check for EUR 1,000,- from the IEEE-CPMT Region 8 Director.

Important Dates:

- **Submission deadline for abstracts: April 1, 2012**
- **Notification of paper acceptance: June 1, 2012**
- **Final paper manuscript due: August 15, 2012**

We look forward to welcoming you to the fourth IEEE-CPMT Electronics Systems Integration Conference ESTC 2012 in Amsterdam!

Eric Beyne
General Chair for ESTC 2012

Ben van der Zon
Executive Chair for ESTC 2012

Mervi Paulasto-Kröckel
Program Chair for ESTC 2012

Organisation and Administration

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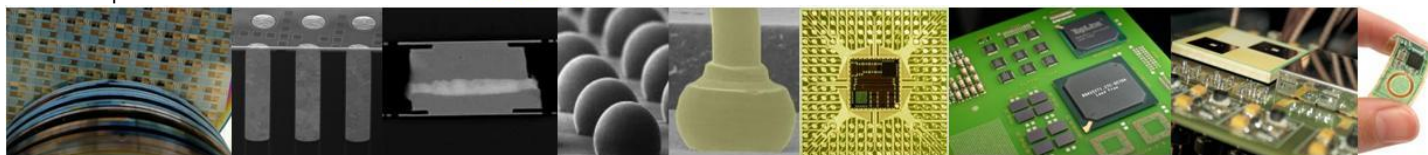


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